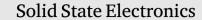
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# Analysis of 1/f and G–R noise in Phosphorene FETs<sup>\*</sup>

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### ARTICLE INFO

ABSTRACT

This work deals with insights into low-frequency noise in phosphorene FETs. In addition to the flicker noise component, which is often reported in the literature, we also look at generation–recombination (G–R) noise. We evaluate the dependence of noise on the number of layers for both armchair (AC) and zigzag (ZZ) orientations. We also extract the noise parameters for this device.

#### 1. Introduction

Keywords:

2D-FET

DFT

Flicker

Phosphorene Noise

Two dimensional Field Effect Transistors (2D–FETs) are being actively investigated for future technology nodes [1]. For efficient use of these devices, understanding the noise behavior is of crucial importance [2]. Noise information also helps us understand the material better. For example, to understand the carrier dynamics in the 2D material systems, low-frequency noise spectroscopy is used as it provides information about trap energy levels and traps concentration values. This insight is highly useful for improving passivation and annealing processes. Noise analysis is equally important for any form of circuit application.

Of the various 2D materials being explored, phosphorene is currently receiving significant attention as it has a combination of useable bandgap and mobility values [3]. Many phosphorene-FET-based experiments have also been reported [4]. However, reports on noise characterizations are quite limited [5], and a better understanding of noise dynamics is required.

In this work, we develop a framework to analyze the low-frequency noise in phosphorene FETs. This work uses first principle based simulations to calculate the material properties including all necessary physical effects while using first-principle calibrated TCAD for FET simulations. We analyze the noise behavior in Phosphorene FETs for multiple layers (N = 1-4) and both the orientations: armchair (AC) and zigzag (ZZ).

# 2. Computational setup

We employ a semi-classical method to calculate the noise in Phosphorene FETs. The detailed method/flow is presented our previous

works [6]. The whole approach is divided into three parts: (a) computation of the electronic properties of single and multilayer Phosphorene using Density Functional Theory (DFT), (b) incorporating the electrical parameters into device simulation using TCAD and (c) noise parameters extraction and analysis.

#### 2.1. Computation of Phosphorene layer electrical parameters

Phosphorene has a puckered honeycomb crystalline symmetric structure. The lattice parameters and orientation are presented in (Fig. 1). We obtained the Phosphorene properties using DFT simulation [7,8].

We used the Meta Generalized Gradient Approximation (MGGA) and TB09LDA functionals which provide accurate results over Localdensity approximations (LDA) and GGA due to the inclusion of exact exchange–correlation. For this band structure calculation, we have used  $14 \times 14 \times 1$  k-points sampling with 98 irreducible, and the density mesh cut-off was set to 150 Rydberg. The obtained bandgap of monolayer Phosphorene is 1.45 eV which exactly matches with experimental data [9]. The bandgap values of two to four layers (2L– 4L) were obtained and found to be in agreement with experimental data [9]. It is found that phosphorene exhibits direct bandgap and there is a dramatic decrease in the bandgap when the number of layers changes from 1L to 3L (Fig. 2) whereas it decreases slightly when the number of layers is increased further. The computed bandgap values and the effective masses of electrons and holes are presented Fig. 2. The obtained effective mass of armchair direction is less than the zigzag.

## 2.2. Device simulation

Extensive work has been done to create a phosphorene material file for TCAD simulations using the result of the DFT simulations. The

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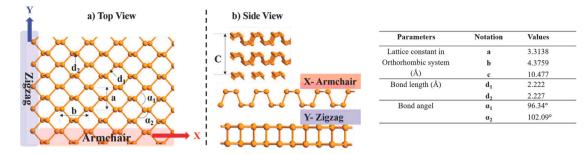
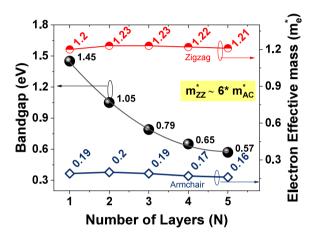


Fig. 1. The crystal structure of Phosphorene is represented and the X-direction (or armchair edge are shown); the Y-direction (zigzag edge are shown). The lattice constants, bond angles, and inter-layer distance are indicated (a) top and (b) side view that parameters values are given in Table form.



**Fig. 2.** The phosphorene bandgap and effective mass values are plotted as a function of the number of layers. AC orientation has less effective mass than ZZ. The bandgap is reduced as the number of layers increases due to a reduction in confinement.

quantum effects are included using a 1D schrödinger equation with calibrated ladder parameters. However, Van der Waals interaction and Source/Drain tunneling are not considered.

#### 2.3. Calibration

The drain current calibration was performed considering a dual gate phosphorene MOSFET. We assumed that contacts (Source/Drain) interfaces are perfect and ohmic. We adjusted the Kinetic Velocity Model (KVM) fitting parameters ( $K_f$ ,  $\alpha_t$ , and  $\alpha_t$ ) and gate metal workfunctions ( $\phi_m$ ) to fix a threshold at 100 nA/µm. Appropriate film thickness ( $t_{si}$ ) and effective oxide thickness ( $t_{ox}$ ) values were also used to match the drain current with NEGF results (Calibrated parameters are listed in Table 1). Fig. 3 shows the calibration of phosphorene FET against NEGF results [10].

#### 2.4. Noise simulation

To calculate the noise in the phosphorene FET, we use the impedance field method [11]. We consider diffusion, flicker, thermal noise. The noise results are calibrated with experimental data as shown in Fig. 4. From the noise calibration, the extracted Hooge parameter value is  $\alpha_h = 5 \times 10^{-4}$  [5] for bulk phosphorene. The flicker noise  $(1/f^{\gamma})$  exponent parameter  $\gamma = 1.1$  and the trap density Ntrap =  $1 \times 10^{12}$  cm<sup>-2</sup>. Layer and orientation-based noise parameters are also calculated while accounting for the thermal noise at high frequencies. In all our noise simulations, we have used an interface trap density of  $1 \times 10^{12}$  cm<sup>-2</sup>.

Table 1					
Material	narameters	used	for	simulation	

Parameters	Notation	Values
Affinity	χ	3.9-4.15 eV
Workfunction	$\phi_m$	4.2 eV
Doping	$N_s$ and $N_d$	$4 \times 10^{18} \text{ cm}^{-3}$
EOT	t <sub>ox</sub>	1 nm
Dielectric constant	$\epsilon_m$	14
Lattice Temperature	Т	300 K
Film thickness	t <sub>si</sub>	5–10 nm
Mobility: AC (ZZ)	Kf	15 (20), 0.1 (0.2), 20 (0.3)
	$\alpha_t, \alpha_b$	0.1 (0.2), 20 (0.3)
Hooge	$\alpha_h$	$1 \times 10^{-5} - 5 \times 10^{-5}$
Trap con.	$N_{trap}$	$1 \times 10^{12} \text{ cm}^{-2}$
DOS	1L - Nce	$8.42 \times 10^{16} \text{ cm}^{-2}$
	5L - Nce	$9.77 \times 10^{16} \text{ cm}^{-2}$
	$A_e$	24.7
Lifetime	$ au_0$	1×10 μs
Ladder parameters	a,b,c	4.1, 0.7, 23.05

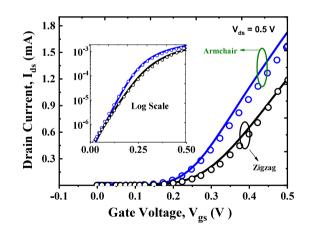
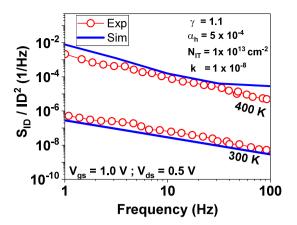


Fig. 3. The calibration of BP-FET against NEGF results [10]. The calibrated parameters are listed in Table 1. Source/drain doped with n-type ( $4 \times 10^{18}$  cm<sup>-3</sup>) and their extension is 14 nm. The contacts are assumed ohmic and trap free.

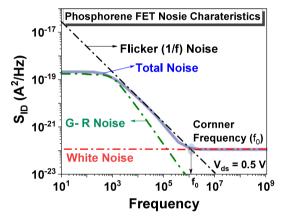
#### 3. Result and discussion

The noise characteristics of phosphorene FET (N = 1L, AC) is plotted as a function of frequency in Fig. 5. The noise power spectral density (PSD) follows the well-known 1/f behavior. The Generation– Recombination (G–R) noise region is visible at lower frequency [12,13].

There are three main noise components dominant in three different frequency regions. For very low frequencies (10 Hz–1 KHz) G–R noise is dominant due to the (single) trapping and de-trapping of carriers. In the range of 1 KHz–100 MHz, the plot shows clear signs of flicker



**Fig. 4.** Noise spectral density  $(S_{ID})$  for bulk phosphorene as a function of frequency and calibrated with [5]. Calibrated noise parameters values are given in the insets. This indicates perfect scaling of  $1/f^{\gamma}$  as expected in conventional noise. This trend is affected by the number of layers considered.



**Fig. 5.** Noise characteristics of Phosphorene FET (1L-AC). It is found that at low frequencies  $S_{ID}$  is high due to a combination of flicker (1/f) and G–R noise. The corner frequency ( $f_{a}$ ) is marked, indicating the dominance of the thermal noise floor.

noise (1/f), which is due to carrier and mobility fluctuation in the phosphorene channel. For higher frequencies (greater than  $f_0$  as marked in Fig. 5), the thermal white noise is dominant.

## 3.1. Layer dependence of extracted $\gamma$ and K

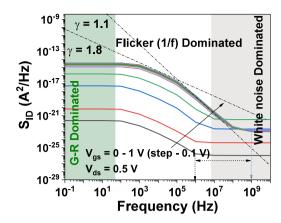
The general expression for flicker noise power spectral density  $(S_{ID})$  can be given as  $S_{ID} = \frac{K}{f_T}$ , where,  $K = W L \alpha_h I_{ds}^2$  while  $\alpha_h$  is the Hooge parameter [14],  $I_{ds}$  is the drain current of the device while W and L are the width and length of the device, respectively.

Fig. 6. shows the extraction of the flicker noise exponent parameter ( $\gamma$ ) at different frequency ranges. We found that  $\gamma$  is frequency dependent for single as well as multi-layer structures. Fig. 6 also shows that gamma is bias dependent, as extracted from  $S_{ID}$  for various bias conditions.

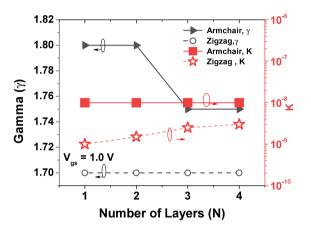
Fig. 7 shows the variation of  $\gamma$  and K, with the number of layers as well as for different orientations (AC/ZZ). For ZZ,  $\gamma$  is roughly constant but there is a variation in K for different N, whereas for AC,  $\gamma$  varies while K is a constant.

# 3.2. Bias dependence of $S_{ID}$

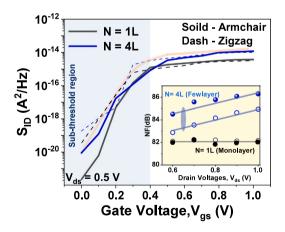
Fig. 8 shows the gate bias (inset shows the drain bias) dependence of the noise power spectral density ( $S_{ID}$ ) in phosphorene FETs.



**Fig. 6.**  $S_{ID}$  of phosphorene device (N = 1L AC) as a function of frequency for a range of gate biases Vgs = 0.0 - 1.0 V and Vds = 0.5 V.  $S_{ID}$  is saturated after Vgs  $\approx$  0.4 V due to the onset of strong inversion.  $\gamma$  is also a function of bias.

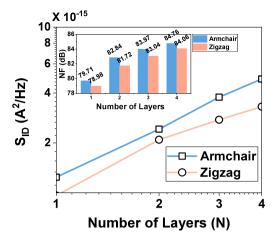


**Fig. 7.** The gamma ( $\gamma$ ) and K values are calculated for different layers. For zigzag orientation  $\gamma = 1.7$  is constant but K varies with number of layers. For armchair orientation, on the other hand, K is constant but  $\gamma$  varies with number of layers.  $S_{ID} = N K/(f^{\gamma})$  where, N is number of layers.



**Fig. 8.** Noise spectrum plotted as a function of gate and drain bias. It is seen that in the subthreshold region,  $S_{ID}$  increases exponentially due to more G–R and diffusion noise. However, drain bias dependence varies with the number of layers. For N = 1L the noise values saturate perfectly due to the very thin nature, whereas for N = 4L it keeps increasing due to more inherent carrier fluctuation than the 1L.

*Gate bias*: In lower gate bias or in the sub-threshold region (shaded)  $S_{ID}$  increases exponentially due to higher carrier fluctuation.  $S_{ID}$  saturates at higher  $V_{gs}$  for all combinations (1L–4L and AC/ZZ).



**Fig. 9.**  $S_{ID}$  for phosphorene with different layers. ZZ shows good noise performance over a wide frequency range and for different layer numbers. The inset figure shows the noise figure in the dB for different layers. Since, the noise increases with increasing number of layers.

*Drain bias:* Inset of Fig. 8 shows that for the monolayer case the noise figure is constant for varying  $V_{ds}$  due to the very thin channel, whereas for N = 4L the noise figure increases with  $V_{ds}$  due to more inherent carrier fluctuation than the 1L.

### 3.3. Layer dependence of $S_{ID}$

Fig. 9 shows that AC has slightly higher noise than ZZ orientation. This is because the higher conductivity for AC results in a higher thermal noise floor. This is true irrespective of the layer number. Due to the addition of volume noise,  $S_{ID}$  rises linearly as the layer size grows, while the monolayer case (N = 1L) only contains surface noise. It also shows the Noise Figure (NF in dB) trends in the inset.

#### 4. Conclusion

Through a detailed noise analysis for Phosphorene FETs, we show that for these devices  $S_{ID}$  increases with number of layers due to increased charge fluctuation. Also, ZZ has better noise performance than AC for all layer numbers. The Hooge model parameters are also extracted and reported for various combinations. Our analysis suggests that Zigzag monolayer Phosphorene gives the best noise performance for device applications among all possible structures with this material.

## Declaration of competing interest

The authors declare that there is no conflict of interest.

#### Data availability

Data will be made available on request.

## Acknowledgments

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